

# PT-TG-3500F

## Ultra Soft Thermal Pad

REACH

RoHS

UL

### Features

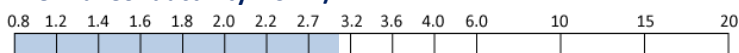
Very good thermal conductivity

Fiberglass on one side

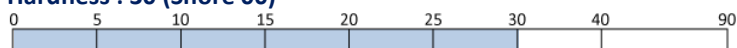
Non deforming

Electrical insulation

**Thermal Conductivity : 3 W / mK**



**Hardness : 30 (Shore 00)**



### Applications

Best for high power applications

Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless

Hub, DDR II Module, DVD Applications, Handset applications etc.

### Thermal Resistance VS. Pressure VS. Deflection

Pressure (psi)	R(°C-in <sup>2</sup> /W)	Deflection(%)
10		
30		
50		

### Properties

Properties	TG-A3500F	Unit	Tolerance	Test Method
Thermal Conductivity	3	W / mK	±0.35	ASTM D5470
Thickness	0.5~8.0	mm	-	ASTM D374
	0.0197~0.315	inch	-	ASTM D374
Color	yellow	-	-	Visual
Reinforcement Carrier	Fiberglass	-	-	-
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	> 6	KV / mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	2.3	g / cm <sup>3</sup>	-	ASTM D792
Working Temperature	-50 ~ +150	°C	-	-
Volume Resistance	8x10 <sup>12</sup>	Ohm-m	-	ASTM D257
Elongation	80	%	-	ASTM D412
Standard Shape	Sheet ones	-	-	-
Hardness(Silicone side)	30	Shore 00	±15	ASTM D2240
Need samples?	Pre-cut for different shapes			

### T-Global Technology Co., Ltd

Provide professional thermal engineering solutions and full range of

products.No. 33, Ln. 50, Daren Rd., Taoyuan Dist., Taoyuan City 330, Taiwan T: +886-3-3618899

M: service@tglobal.com.tw W: www.tglobalcorp.com